Benchao Zhu

RESEARCH INTEREST

Electronic Design Automation

EDUCATION

Fudan University Shanghai, CHN

M.E. in Electronics and Information Engineering

September 2022 - June 2025 (expected)

- GPA: 3.46/4.0 Rank: 14/160

Fudan University Shanghai, CHN September 2018 - June 2022

B.E. in Microelectronics Science and Engineering

- GPA: 3.50/4.0 - Rank: 24/146

AWARDS & HONORS

O Xiaomi Special Scholarship, Fudan University (2023)

- Outstanding Students, Fudan University (2023)
- National Encouragement Scholarship, Fudan University (2019, 2020, 2021)

SKILLS

Programming C++, LaTeX, Python, Perl, Shell

Languages Chinese, English

COMPETITIONS

2023 ISPD Contest (Security Closure of Physical Layouts)

First Place

2024 ISPD Contest (GPU/ML-Enhanced Large Scale Global Routing)

Fifth Place

2024 ICCAD Contest (Power and Timing Optimization Using Multibit Flip-Flop)

Fourth Place

PUBLICATIONS

- o Late Breaking Results: Mixed-Cell-Height Detailed Placement under Multi-Cell Spacing Constraints Benchao Zhu, Zheng Zeng, and Jianli Chen 61th ACM/IEEE Design Automation Conference (DAC), 2024.
- Effective Analytical Placement for Advanced Hybrid-Row-Height Circuit Designs Yuan Wen, Benchao Zhu, Zhifeng Lin, and Jianli Chen 29th Asia and South Pacific Design Automation Conference (ASPDAC), 2024.
- o Mixed-cell-height Placement with Minimum-Implant-Area and Drain-to-Drain Abutment Constraints Guohao Chen, Zheng Zeng, Benchao Zhu, Jiawei Li, Kun Wang, Jun Yu, and Jianli Chen 60th ACM/IEEE Design Automation Conference (DAC), 2023.

SELECTED COURSES

Postgraduate:

Discrete Mathematics & Optimal Decision (A), Digital Signal Processing VLSI Design (B)

Undergraduate:

 $Analog\ Circuit\ (A), Fundamentals\ of\ Digital\ Logic\ (A), Signal\ and\ Communication\ System\ (A)$